nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number					
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		1PS70SB84 Part Description					
		SMD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
			TEST Pre- and Post-Stress				
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
+ []		JESD22-A113	N/A	see below	all parts	see below	
		Bake Tamb = $125 ^{\circ}\text{C}$	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet					
# B1	Bias	reverse voltage ^[1]	1000 hours	116	9280	0	
	тс	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0	
		JESD22-A102					
	AC	Tamb = 121 °C, RH = 100 %					
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0	
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^{[1], [2]}					
# A2 alt	Temperature Reverse Bias	· · · · · · · · · · · · · · · · · · ·	1000 hours	170	13600	0	
		MIL-STD-750 Method 1037					
	IOL	ton = toff, devices powered to insure ΔTj =	10001	170	10000	•	
# A5	Intermittent Operating Life	100 °C 101 15000 cycles	1000 hours	170	13600	0	
	RSH						
# C8	Resistance to Solder Heat	JESD22-A111 260 °C + 5 °C	10 s	130	2000	0	
+ L0	SD	200 0 + 5 0	10.5	130	3900	0	
# C10	Solderability	J-STD-002		363	3630	0	
	,	des have to be considered (thermal runaway).		202	5020	U	

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
	Beneticity	200			21152.05

© 2022 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com